

SPECIFICATION AMENDMENTS:

Please replace the paragraph bridging pages 8 and 9 with the following amended paragraph:

--The metal wire 16 is connected to the upper surface 14Aa of the inner connecting portion 14A at a position spaced apart by a distance L1 from the boundary between the inner connecting portion 14A and the outer connecting portion 14B (the position of step 14S) toward the central portion side of the semiconductor device 11 (semiconductor chip 15 side). On the upper surface 14Ba of the ~~of the~~ outer connecting portion 14B, a groove 14C is provided perpendicular to the longitudinal direction of the lead terminal portion 14. The inside of the groove 14C is filled with the sealing resin 17.--